

2SK2737

Silicon N Channel MOS FET High Speed Power Switching

REJ03G1031-0400

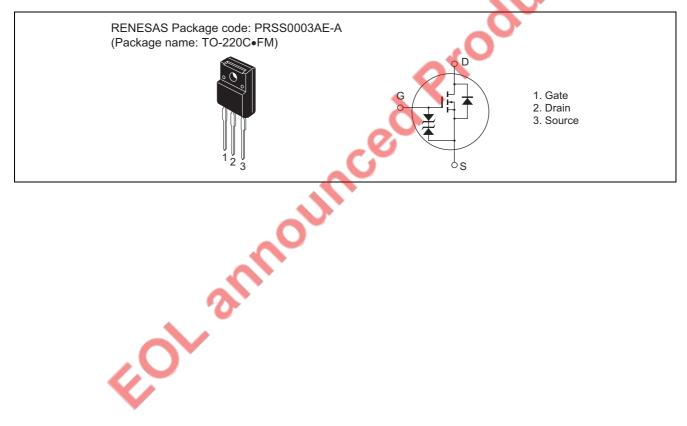
(Previous: ADE-208-533B)

Rev.4.00 Sep 07, 2005

Features

- Low on-resistance $R_{DS(on)} = 10 \text{ m}\Omega \text{ typ.}$
- 4 V gate drive devices.
- High speed switching

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	30	V
Gate to source voltage	V_{GSS}	±20	V
Drain current	I _D	45	A
Drain peak current	I _{D(pulse)} Note1	180	A
Body-drain diode reverse drain current	I _{DR}	45	A
Channel dissipation	Pch ^{Note2}	30	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	−55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1 %

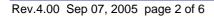
2. Value at Tc = 25°C

Electrical Characteristics

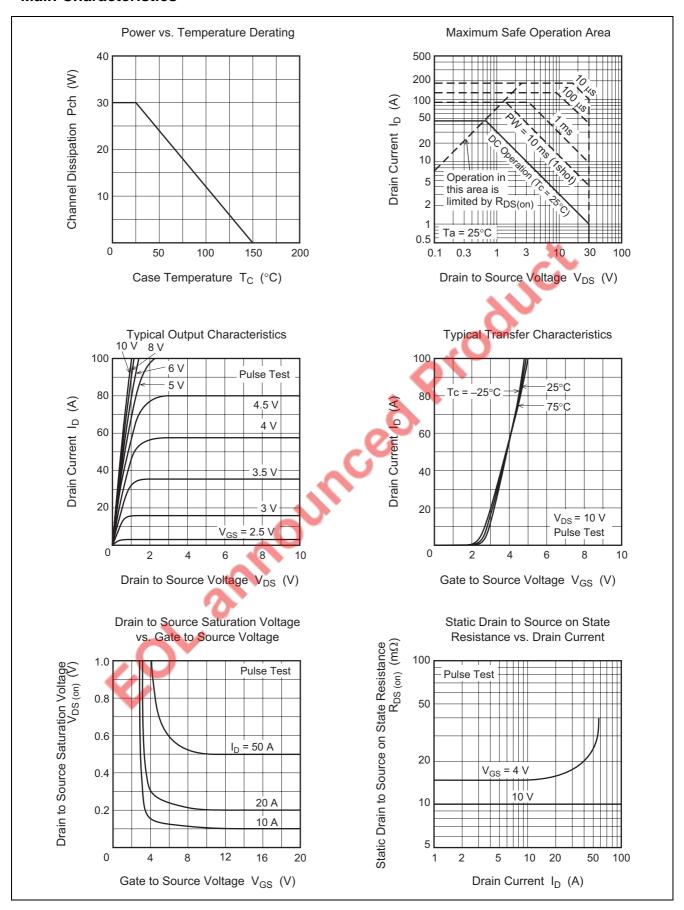
 $(Ta = 25^{\circ}C)$

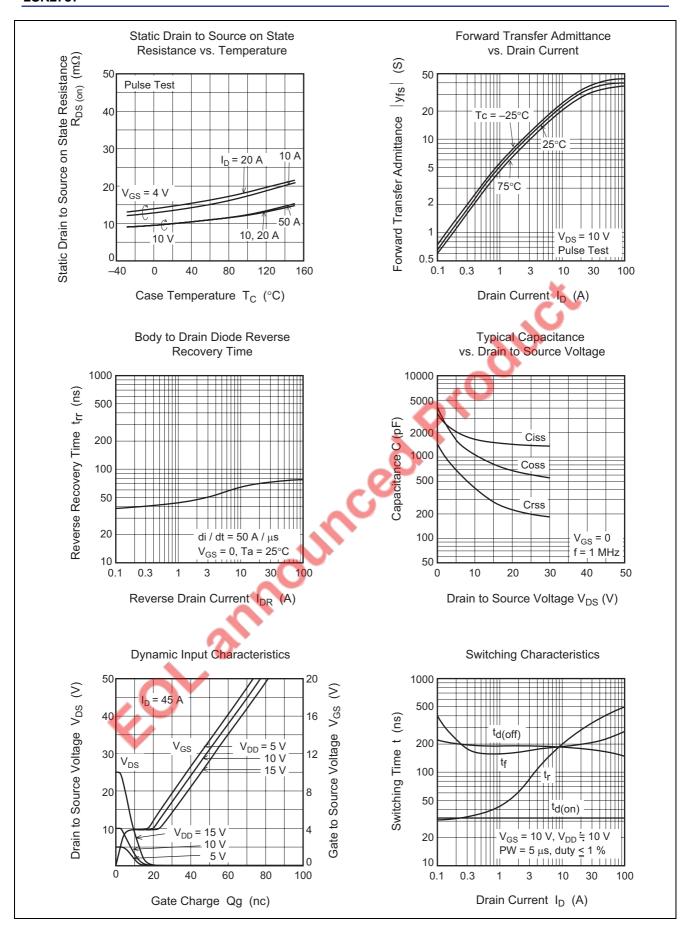
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	30	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	_	_	V	$I_G = \pm 100 \mu A, V_{DS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	10	μΑ	$V_{DS} = 30 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	V _{GS(off)}	1.0	_	2.0	V	$I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}^{\text{Note3}}$
Static drain to source on state	R _{DS(on)}	_	10	14	mΩ	$I_D = 20 \text{ A}, V_{GS} = 10 \text{ V}^{\text{Note3}}$
resistance	R _{DS(on)}	_	15 🦱	25	mΩ	$I_D = 20 \text{ A}, V_{GS} = 4 \text{ V}^{\text{Note3}}$
Forward transfer admittance	y _{fs}	20	30	_	S	$I_D = 20 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note3}}$
Input capacitance	Ciss	_	1570	_	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$
Output capacitance	Coss	—, «	1100	_	pF	f = 1MHz
Reverse transfer capacitance	Crss	-	410	_	pF	
Turn-on delay time	t _{d(on)}		32	_	ns	$V_{GS} = 10 \text{ V}, I_D = 20 \text{ A},$
Rise time	t _r	O	300	_	ns	$R_L = 0.5 \Omega$
Turn-off delay time	t _{d(off)}	<u> </u>	180	_	ns	
Fall time	tı	_	200	_	ns	
Body-drain diode forward voltage	V_{DF}	_	1.0	_	V	I _F = 45 A, V _{GS} = 0
Body-drain diode reverse	T t _{rr}	_	75	_	ns	I _F = 45 A, V _{GS} = 0
recovery time						$di_F/dt = 50A/\mu s$

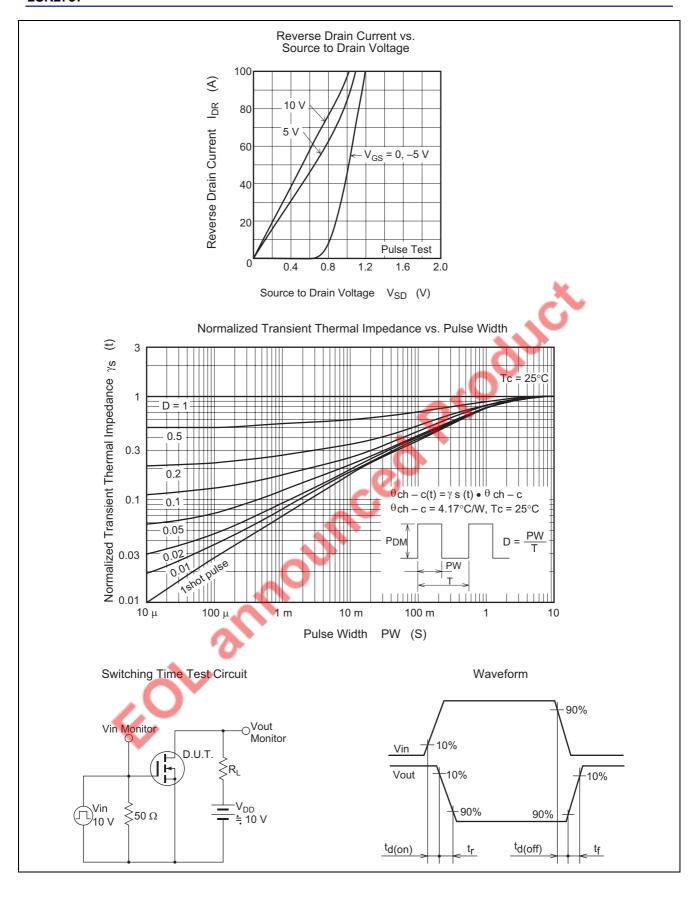
Note: 3. Pulse test



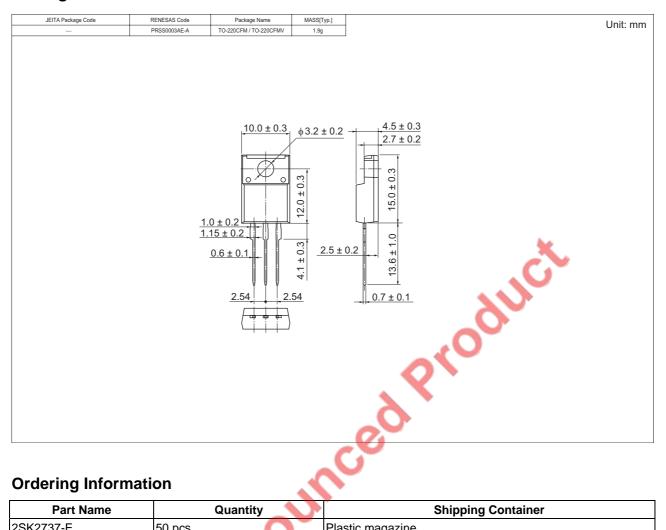
Main Characteristics







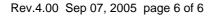
Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
2SK2737-E	50 pcs	Plastic magazine

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.



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